MIL-PRF-38535 Rev F Changes

1. This entire document has editorial changes which update the document to the requirements of MIL-STD-961. These changes were not highlighted so as not to be confused with the technical changes in this revision.

2. Page 1, Preamble – Delete MIL-M-38510 from Appendix A reference. There are no more manufacturers producing JAN parts to Appendix A.

3. Page 3, 2.3 Delete reference to JEDEC Publication 109 and replace with JEDEC JESD 31. Pub 109 has been canceled.

4. Page 4, 3.2.1 Delete reference to JEDEC Publication 109 and replace with JEDEC JESD 31. Pub 109 has been canceled.

5. Page 8, 3.4.1.6 Addition - Major changes as they affect test optimization. Clarification, it was always intended that manufacturers were analyzing test optimization after major changes.

6. Page 11, 3.6.2.2.1 Deletion - All M38510 manufacturers are building devices as QML parts. Appendix A is intended for manufacturers who are building 883 compliant product.

7. Page 11, 3.6.2.1 Deletion – Note, There are no more manufacturers producing JAN parts to appendix A. QML marking per 3.6.3.

8. Page 13, 3.6.9 Addition – Reference to MIL-STD-1285.

9. Page 14, 4.4 Addition - Paragraph required per MIL-STD-961.

10. Page 15, TABLE IA Addition – J.3.6 reference to Screen 11.

11. Page 17, TABLE II Addition - clarification.

12. Page 18, TABLE V Addition - clarification.

13. Page 19, 5.1 Addition - Paragraph required per MIL-STD-961

14. Page 19, 6.1 Addition - Paragraph required per MIL-STD-961

15. Page 19, 6.2 Addition - Paragraph required per MIL-STD-961

16. Page 19, 6.3 Addition - Paragraph required per MIL-STD-961

17. Pages 19 – 22, 6.4 Renumbered paragraphs for terms and definition.

18. Page 22, 6.4.31 & 32 Addition - Definitions of class B & S.

19. Page 25 - 27, 6.8 Addition - List of acronyms.

20. Page 27, 6.9 Addition – Environmentally preferable material.

21. Page 28, A.1.1 Addition – Clarification, Appendix A is for MIL-STD-883 compliant product. All QPL suppliers are now supplying under QML.

22. Page 28, A.2.2.1 Delete reference to MIL-STD-280 and replace with MIL-HDBK-505.

23. Page 29, A.2.3 Correction - ASTM address.

24. Page 29, A.2.3 Delete reference to JEDEC Publication 109 and replace with JEDEC JESD 31. Pub 109 has been canceled.

25. Page 29, A.2.3 Correction - ANSI address.

26. Page 29, A.2.3 Correction – JEDEC address.

27. Page 30, A.2.3 Addition - ISO standards for clean rooms, replacing FED-STD-209.

28. Page 31, A.3.1.3 Delete reference to MIL-STD-280 and replace with MIL-HDBK-505.

29. Page 34, A.3.2 Addition – SMD acronym.

30. Page 34, A.3.2.2 Clarification - Alternate Die Fab requirements.

31. Page 35, A.3.3 Addition - Process Monitor Program to classification of requirements. Inadvertently left out of table.

32. Page 36, A.3.3.1 Delete reference to JEDEC Publication 109 and replace with JEDEC JESD 31. Pub 109 has been canceled.

33. Page 38, A.3.4.1.4a Deletion - ESD re-marking exception – ESD marking not required per 3.6.7.2.

34. Page 41, A.3.5.5 Addition - Internal conductors add copper- JC13.2 requested.

35. Page 45, A.3.5.6.3 Deletion - TM2022 solderability (has not been updated) reference no longer equivalent to TM2003.

36. Page 48, A.3.5.7 Addition – Note concerning Rome Labs letter.

37. Page 50, A.3.6.2 Deletion - 38510 reference, there are no more non-QML 38510 suppliers.

38. Page 51, A.3.6.7 Addition - “D” cert mark to DMS for MIL-STD-883 compliant product.

39. Page 53, A.4 Change - Update section title per 961.

40. Page 56, A.4.3.5 Deletion - “For JAN production…” All JAN product is now being built under QML rather than Appendix A.

41. Page 59, A.4.5.4.1.2 Deletion – Note, this was used to allow for the switching of testing coverage from inspection lot to fab lot and should no longer be applicable. This was used as a transition period.

42. Page 68, A.4.8.1.1.7 Change - FED-STD-209 with ISO 14644-1 and ISO 14644-2.

43. Page 76, A.5.1 Addition - Packaging paragraph per 961.

44. Page 78, A.6.2 Change – Update acquisition requirements per 961.

45. Page 80, B.4 Change - Update section title per 961.

46. Page 83, C.2.2 Change - ASTM 1032 replace by ASTM 1892 per JC 13.4.

47. Page 84, C.3.4.1 Change - ASTM 1032 reference with ASTM 1892 per JC 13.4.

48. Page 92, D.1.1 Addition - Paragraph required per MIL-STD-961

49. Page 100, F.4 Change - Update section title per 961.

50. Page 115, H.2.1 Addition – JESD 28 IC Latch-up Test.

51. Page 115, H.2.1 Addition - ASTM G21 For Fungus Testing.

52. Page 127, TABLE H-IIA Change JESD 17 to JESD 78

53. Page 128, TABLE H – IIB Addition - Group 8, ASTM G21 Fungus Test Reference.

54. Page 128, TABLE H – IIB Change JESD 17 to JESD 78

55. Page 129, H.3.3.1 Deletion - QPL manufacturers not transition to QML – There are none left.

56. Page 133, J.3.2 Addition – 3.4.1.4w reference to Internal visual.

57. Page 134, J.3.9 Change – “control” to “TCI testing”.

58. Page 134, J.3.9.2 Change – “standard” to “end-of-line” and “control” to “TCI testing”.

59. Page 134, J.3.10 Change – “QCI” to “TCI”.